



## Material Content Data Sheet



<b>Sales Product Name</b>		IDH05SG60C		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000629884						
<b>Package</b>		PG-TO220-2-1		<b>Weight*</b>		1965.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.807	0.04		411	
	noble metal	gold	7440-57-5	0.025	0.00		13	
	non noble metal	tin	7440-31-5	0.007	0.00	0.04	3	427
leadframe	non noble metal	iron	7439-89-6	1.343	0.07		683	
	inorganic material	phosphorus	7723-14-0	0.403	0.02		205	
wire	non noble metal	copper	7440-50-8	1341.263	68.22	68.31	682244	683132
	non noble metal	aluminium	7429-90-5	0.162	0.01	0.01	82	82
encapsulation	organic material	carbon black	1333-86-4	9.109	0.46		4633	
	plastics	epoxy resin	-	100.198	5.10		50967	
	inorganic material	silicondioxide	60676-86-0	497.954	25.33	30.89	253289	308889
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7369	7369
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	0	101
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

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